

WEICAI LCD/LED Bonding Machine

CR-816SH-19m







Introducing the CR-816SH WEICAI COF Bonding Machine Precision, Performance, and Reliability for Screen Repairs.

- 1. The CR-816SH WEICAI COF Bonding Machine is a high-precision device.
- 2. It is designed for advanced LCD and LED screen repairs.
- 3. Suitable for both small-scale and industrial applications.
- 4. Excels in COF (Chip on Film) bonding, ensuring flawless connections between flexible circuits and display panels.
- 5. Features state-of-the-art technology and a user-friendly interface.
- 6. Offers reliable and efficient performance.
- 7. Preferred choice for professionals aiming to enhance screen repair quality and productivity.

Device Model	CR-816SH-19M
Hot Press Machine	Hot Press Machine
Device Description	Double Screen repair equipment, LCD repair equipment, COF/TAB bonding equipment, etc.
Device Uses	This product is used in a variety of FPC, COF, TAB and LCD Panel and PCB combination bonding, is reflected in a variety of sizes LCD vertical, horizontal, vertical band, horizontal belt, black belt, black, colored thread, ribbon, multi-line, black, black and white, vertical half display,horizontal half breakdown maintenance.
	Single head ,single pneumatic device, single temperature control.
Device Features	Multi-speed pulse source design to meet the power requirements of diversified product pressure.
Applicable LCD panel specifications	15"-65"(Platform expandable).
Applicable LCD panel thickness	0.3MM-1.1MM[Single glass].
Panel Type	TFT TECHNOARTS
Bonding IC number	One/PANEL
Bonding Direction	X or Y Unidirection
Bonding Head Size	Replaceable blade according to IC specifications (The original machine is equipped (50*1.4*10mm).
Production Beat	TAB, 100pcs/H
Bonding Accuracy	±1.5μm (support 4K)
Highest Positioning Accuracy Setting	±0.5µm

Equipment Requirements work environment	Clean, Dust-Free, Clean Room.
Supply Pressure	0.1~0.7Mpa Dry air source
Power Supply	AC 220V±10%,50HZ,3500W
Pneumatic Device	Air TAC Original precision cylinder
Pressure System	Pressure system parallel bar structure eliminates the weight of the indenter,pressure minimum accuracy can up to 0.1 KG,pressure components are using SMC precision components.
Heating Method	Pulse (rapid heating/cooling and auxiliary cool <mark>i</mark> ng).
Brand	WEICAI
Temperature Control System	Adjustable temperature rise curve with high precision PID auto-tuning.
	The PeakTemperature : within +/-1degrees Celsius.
	Room temperature time to 180 degrees the response time within 2-3 seconds.
Hot Pressing Head	Material: Titanium Alloy
	Metal Properties:SUS440C
	Origin: United States
	Plane Precision (Hot Pressing Surface) :0.001mm.
Thermocouple Type	Plane Thickness 0.5 (keep 3 times grinding). K Type Original US OMEGA Wire.
Industrial Control Unit Programme	Display Control
Touch Unit	Display control touch screen.

Image Unit	COF Counterpoint: Down counterpoint (Optical Path: Lens> Quartz> ITO Electrode> COF)
	PCB Alignment: None (Optional Installation)
	Number of lens: 2
	Microscope: 200-300 continuous zoom
	COF Display Screen: 19 Inches HD
	PCB Front Camera:None (Optional Installation).
	PCB Alignment Display: Switchable.
COF trimming unit	Origin: China
	Rail Type: U-Rail
	Accuracy: 0.01
	Adjustable Direction: X/Y/R
	R Stroke: Coarse Adjustment 360 Degrees, Fine Adjustment +/- 5 Degrees.
COF Fixture	COF mechanical clamping type ,Z-direction tilt radius micrometer finetuning.
Lens Spinner unit	Control mode: X / Y / Z micrometer control.
	Focus Adjustment: Manually adjust the focus.
Silicone / Teflon	Manual switching positio.
LCD Stage (platform)	Manual slide movement.
Bonding Head Alignment	The cylinder can be set to stop in any position in the upper and lower directions.
Control Method	Touch screen + button operation
Rated Voltage	AC 180-220V
Parameter setting	Can store multiple sets of hot pressing parameters as needed.
Peak Power	400-1100W (can support 68X1.4X10 wide bonding head).
Maximum Power	1100W
Actual Power	580W
Body Size	1800X1200x1520mm(L*W*H)
Net Weight of Equipment	430KG
Number of Packages	2

Equipment Packaging	Wooden boxes, non-logs (material is glued board, no fumigation is required for export).	
Package Size and Gross Weight	□920X920X1660mm (L*W*H) 320KG	
	□1920X520X960mm (L*W*H) 110KG	
The following nicture is the device after nackaged		

